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CLAIMS

1. An oral preparation comprising (a) an organic acid, inorganic acid, or mixtures thereof, and (b) a fluoride ion supplying compound, wherein a light scattering layer is formed inside enamel of the teeth when the oral preparation is applied to teeth.

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- 2. The oral preparation according to claim 1, wherein the light scattering layer is formed at a depth of 500 μm or less from the surface of the enamel.
 - 3. The oral preparation according to claim 1, wherein the organic acid and/or inorganic acid is at least one selected from the group consisting of acetic acid, lactic acid, malic acid, tartaric acid, citric acid, glycollic acid, succinic acid, phosphoric acid, and mixtures thereof.
 - 4. The oral preparation according to claim 1, wherein the fluoride ion supplying compound is at least one selected from the group consisting of sodium fluoride, sodium monofluorophosphate, stannous fluoride, lithium fluoride, ammonium fluoride, and mixtures thereof.
 - 5. The oral preparation according to claim 1, wherein the oral preparation further comprises a potassium ion.
 - 6. The oral preparation according to claim 5, wherein a content of the potassium ion ranges from 0.1 to 5 wt. %.

- 7. The oral preparation according to claim 5, wherein the oral preparation comprises:
- (A) from 0.02 to 0.2 wt. % (in terms of fluorine atom) of the fluoride ion supplying component;
 - (B) from 0.03 to 0.5 mol/kg of a combination of malic acid and/or tartaric acid with salts thereof;
 - (C) from 0.03 to 0.5 mol/kg of potassium ion; and
 - (D) water;

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- and, a 30 wt.% dilution of the oral preparation with water has a pH ranging from 3 to 5.5.
 - 8. A chewing gum comprising (a) an organic acid, inorganic acid, or mixtures thereof, and (b) a fluoride ion supplying compound, wherein a light scattering layer is formed inside enamel of the teeth when the chewing gum is applied to teeth.
- 9. The chewing gum according to claim 8, wherein the light scattering layer is formed at a depth of 500 μm or less from the 20 surface of the enamel.